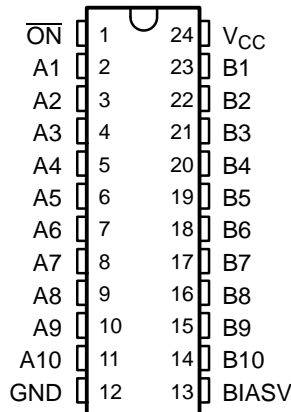


## FEATURES

- High-Bandwidth Data Path (Up To 500 MHz <sup>(1)</sup>)
  - 5-V Tolerant I/Os With Device Powered Up or Powered Down
  - Low and Flat ON-State Resistance ( $r_{on}$ ) Characteristics Over Operating Range ( $r_{on} = 4.5 \Omega$  Typ)
  - Rail-to-Rail Switching on Data I/O Ports
    - 0- to 5-V Switching With 3.3-V  $V_{CC}$
    - 0- to 3.3-V Switching With 2.5-V  $V_{CC}$
  - B-Port Outputs Are Precharged by Bias Voltage (BIASV) to Minimize Signal Distortion During Live Insertion and Hot Plugging
  - Supports PCI Hot Plug
  - Bidirectional Data Flow With Near-Zero Propagation Delay
  - Low Input/Output Capacitance Minimizes Loading and Signal Distortion ( $C_{io(OFF)} = 3.5$  pF Typ)
- (1) For additional information regarding the performance characteristics of the CB3Q family, refer to the TI application report, *CBT-C, CB3T, and CB3Q Signal-Switch Families*, literature number SCDA008.
- Fast Switching Frequency ( $f_{ON} = 20$  MHz Max)
  - Data and Control Inputs Provide Undershoot Clamp Diodes
  - Low Power Consumption ( $I_{CC} = 0.75$  mA Typ)
  - $V_{CC}$  Operating Range From 2.3 V to 3.6 V
  - Data I/Os Support 0- to 5-V Signaling Levels (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V)
  - Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs
  - $I_{off}$  Supports Partial-Power-Down Mode Operation
  - Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
  - ESD Performance Tested Per JESD 22
    - 2000-V Human-Body Model (A114-B, Class II)
    - 1000-V Charged-Device Model (C101)
  - Supports Both Digital and Analog Applications: PCI Interface, Differential Signal Interface, Memory Interleaving, Bus Isolation, Low-Distortion Signal Gating

DBQ, DGV, OR PW PACKAGE  
(TOP VIEW)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**SN74CB3Q6800**  
**10-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS**  
**2.5-V/3.3-V LOW-VOLTAGE HIGH-BANDWIDTH BUS SWITCH**

SCDS142A—OCTOBER 2003—REVISED MARCH 2005

**DESCRIPTION/ORDERING INFORMATION**

The SN74CB3Q6800 is a high-bandwidth FET bus switch utilizing a charge pump to elevate the gate voltage of the pass transistor, providing a low and flat ON-state resistance ( $r_{on}$ ). The low and flat ON-state resistance allows for minimal propagation delay and supports rail-to-rail switching on the data input/output (I/O) ports. The device also features low data I/O capacitance to minimize capacitive loading and signal distortion on the data bus. Specifically designed to support high-bandwidth applications, the SN74CB3Q6800 provides an optimized interface solution ideally suited for broadband communications, networking, and data-intensive computing systems.

The SN74CB3Q6800 is a 10-bit bus switch with a single output-enable ( $\overline{ON}$ ) input. When  $\overline{ON}$  is low, the 10-bit bus switch is ON and the A port is connected to the B port, allowing bidirectional data flow between ports. When  $\overline{ON}$  is high, the 10-bit bus switch is OFF and a high-impedance state exists between the A and B ports. The B port is precharged to bias voltage (BIASV) through the equivalent of a 10-k $\Omega$  resistor when  $\overline{ON}$  is high, or if the device is powered down ( $V_{CC} = 0$  V).

During insertion (or removal) of a card into (or from) an active bus, the card's output voltage may be close to GND. When the connector pins make contact, the card's parasitic capacitance tries to force the bus signal to GND, creating a possible glitch on the active bus. This glitching effect can be reduced by using a bus switch with precharged bias voltage (BIASV) of the bus switch equal to the input threshold voltage level of the receivers on the active bus. This method ensures that any glitch produced by insertion (or removal) of the card does not cross the input threshold region of the receivers on the active bus, minimizing the effects of live-insertion noise.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry prevents damaging current backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down,  $\overline{ON}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

**ORDERING INFORMATION**

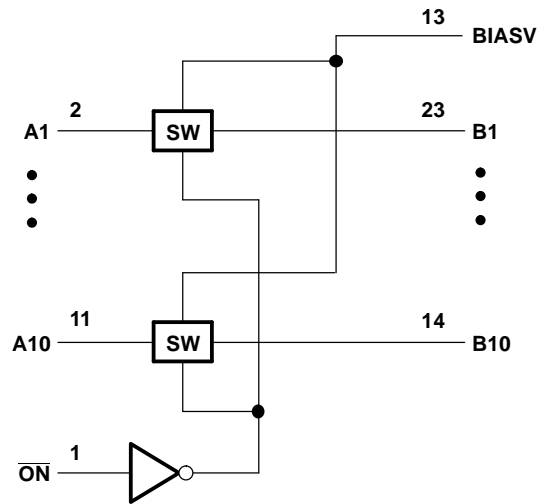
$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP (QSOP) – DBQ	Tape and reel	SN74CB3Q6800DBQR	CB3Q6800
	TSSOP – PW	Tube	SN74CB3Q6800PW	BY800
		Tape and reel	SN74CB3Q6800PWR	
	TVSOP – DGV	Tape and reel	SN74CB3Q6800DGVR	BY800

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

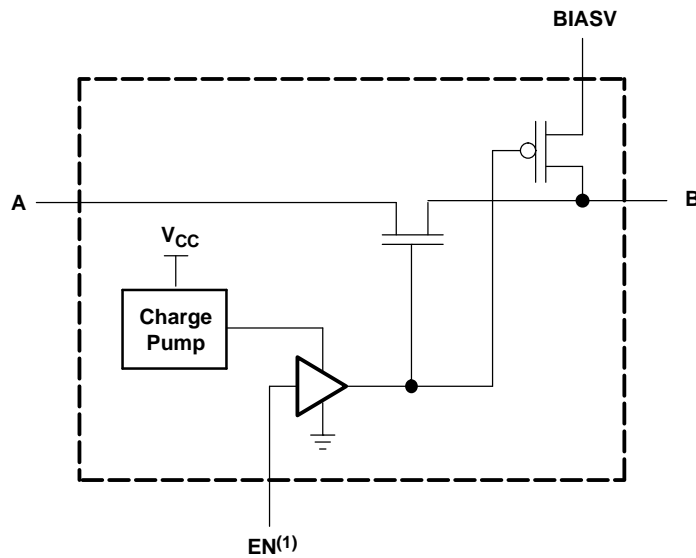
**FUNCTION TABLE**

INPUT $\overline{ON}$	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect B port = BIASV

**LOGIC DIAGRAM (POSITIVE LOGIC)**



**SIMPLIFIED SCHEMATIC, EACH FET SWITCH (SW)**



(1) EN is the internal enable signal applied to the switch.

**SN74CB3Q6800**  
**10-BIT FET BUS SWITCH WITH PRECHARGED OUTPUTS**  
**2.5-V/3.3-V LOW-VOLTAGE HIGH-BANDWIDTH BUS SWITCH**

SCDS142A—OCTOBER 2003—REVISED MARCH 2005

**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	4.6	V
BIASV	BIAS supply voltage range	-0.5	7	V
$V_{IN}$	Control input voltage range <sup>(2)(3)</sup>	-0.5	7	V
$V_{I/O}$	Switch I/O voltage range <sup>(2)(3)(4)</sup>	-0.5	7	V
$I_{IK}$	Control input clamp current		$V_{IN} < 0$	-50 mA
$I_{I/OK}$	I/O port clamp current		$V_{I/O} < 0$	-50 mA
$I_{I/O}$	ON-state switch current <sup>(5)</sup>			±64 mA
	Continuous current through $V_{CC}$ or GND			±100 mA
$\theta_{JA}$	Package thermal impedance <sup>(6)</sup>	DBG package		61
		DGV package		86
		PW package		88
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4)  $V_I$  and  $V_O$  are used to denote specific conditions for  $V_{I/O}$ .
- (5)  $I_I$  and  $I_O$  are used to denote specific conditions for  $I_{I/O}$ .
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.

**Recommended Operating Conditions<sup>(1)</sup>**

		MIN	MAX	UNIT	
$V_{CC}$	Supply voltage	2.3	3.6	V	
BIASV	Bias supply voltage	0	5	V	
$V_{IH}$	High-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	5.5	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2	5.5	
$V_{IL}$	Low-level control input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0	0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0	0.8	
$V_{I/O}$	Data input/output voltage	0	5.5	V	
$T_A$	Operating free-air temperature	-40	85	°C	

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004. BIASV is a supply voltage, not a control input.

### Electrical Characteristics<sup>(1)</sup>

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP <sup>(2)</sup>	MAX	UNIT
$V_{IK}$		$V_{CC} = 3.6\text{ V}$ ,	$I_I = -18\text{ mA}$				-1.8	V
$I_{IN}$	Control inputs	$V_{CC} = 3.6\text{ V}$ ,	$V_{IN} = 0\text{ to }5.5\text{ V}$				±1	μA
$I_O$	B port	$V_{CC} = 3\text{ V}$ ,	BIASV = 2.4 V, $V_O = 0$ ,	Switch OFF, $V_{IN} = V_{CC}\text{ or GND}$			0.2	mA
$I_{OZ}^{(3)}$		$V_{CC} = 3.6\text{ V}$ ,	$V_O = 0\text{ to }5.5\text{ V}$ , $V_I = 0$ ,	Switch OFF, $V_{IN} = V_{CC}\text{ or GND}$			±1	μA
$I_{off}$		$V_{CC} = 0$ ,	$V_O = 0\text{ to }5.5\text{ V}$ ,	$V_I = 0$			1	μA
$I_{CC}$		$V_{CC} = 3.6\text{ V}$ ,	$I_{I/O} = 0$ , Switch ON or OFF,	$V_{IN} = V_{CC}\text{ or GND}$		0.75	2	mA
$\Delta I_{CC}^{(4)}$	Control inputs	$V_{CC} = 3.6\text{ V}$ ,	One input at 3 V, Other inputs at $V_{CC}\text{ or GND}$				30	μA
$I_{CCD}^{(5)}$	Per control input	$V_{CC} = 3.6\text{ V}$ ,	A and B ports open, Control input switching at 50% duty cycle			0.38	0.45	mA/ MHz
$C_{in}$		$V_{CC} = 3.3\text{ V}$ ,	$V_{IN} = 5.5\text{ V}, 3.3\text{ V},\text{ or }0$			2.5	3.5	pF
$C_{io(OF)}$ F)	A port	$V_{CC} = 3.3\text{ V}$ ,	Switch OFF, $V_{IN} = V_{CC}\text{ or GND}$ ,	$V_{I/O} = 5.5\text{ V}, 3.3\text{ V},\text{ or }0$		3.5	5	pF
$C_{io(ON)}$		$V_{CC} = 3.3\text{ V}$ ,	Switch ON, $V_{IN} = V_{CC}\text{ or GND}$ ,			9	11	pF
$r_{on}^{(6)}$	$V_{CC} = 2.3\text{ V}$ , TYP at $V_{CC} = 2.5\text{ V}$	$V_I = 0$ ,	$I_O = 30\text{ mA}$			4.5	8	Ω
		$V_I = 1.7\text{ V}$ ,	$I_O = -15\text{ mA}$			4.8	9	
	$V_{CC} = 3\text{ V}$	$V_I = 0$ ,	$I_O = 30\text{ mA}$			4.5	6	
		$V_I = 2.4\text{ V}$ ,	$I_O = -15\text{ mA}$			4.6	8	

- (1)  $V_{IN}$  and  $I_{IN}$  refer to control inputs.  $V_I$ ,  $V_O$ ,  $I_I$ , and  $I_O$  refer to data pins.
- (2) All typical values are at  $V_{CC} = 3.3\text{ V}$  (unless otherwise noted),  $T_A = 25^\circ\text{C}$ .
- (3) For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current.
- (4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.
- (5) This parameter specifies the dynamic power-supply current associated with the operating frequency of a single control input (see Figure 2).
- (6) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

### Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	TEST CONDITIONS	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
				MIN	MAX	MIN	MAX	
$f_{ON}^{(1)}$		$\overline{ON}$	A or B		10		20	MHz
$t_{pd}^{(2)}$		A or B	B or A		0.135		0.225	ns
$t_{pZH}$	BIASV = GND	$\overline{ON}$	A or B	1.5	8.5	1.5	6.7	ns
$t_{pZL}$	BIASV = 3 V			1.5	8.5	1.5	6.7	
$t_{pHZ}$	BIASV = GND	$\overline{ON}$	A or B	1	5	1	5	ns
$t_{pLZ}$	BIASV = 3 V			1	6.9	1	6.9	

- (1) Maximum switching frequency for control input ( $V_O > V_{CC}$ ,  $V_I = 5\text{ V}$ ,  $R_L \geq 1\text{ M}\Omega$ ,  $C_L = 0$ ).
- (2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

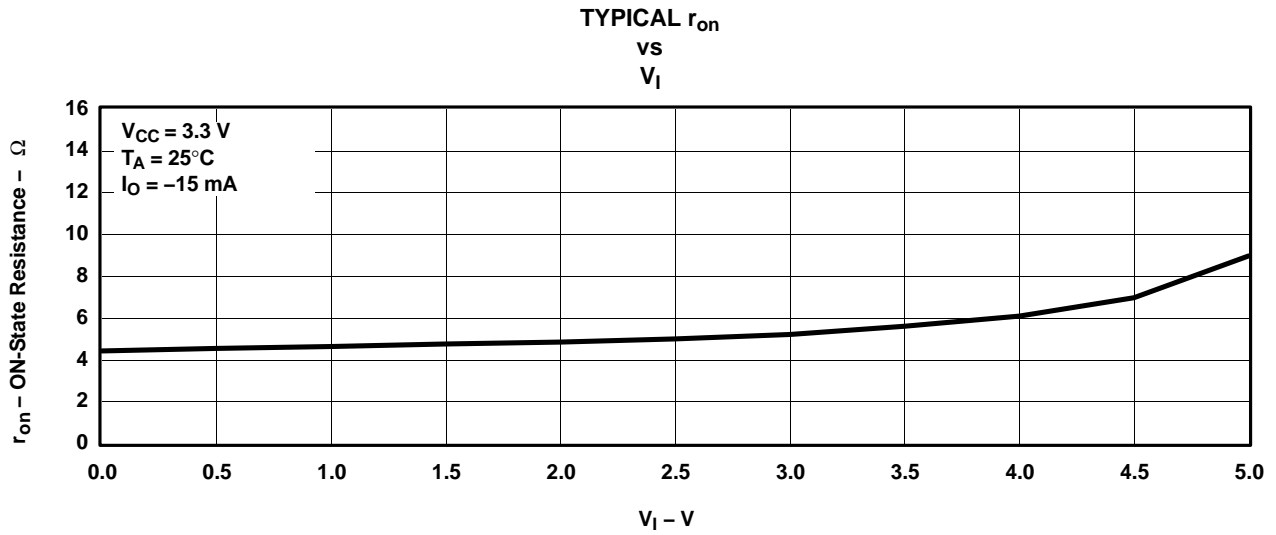


Figure 1. Typical  $r_{on}$  vs  $V_I$

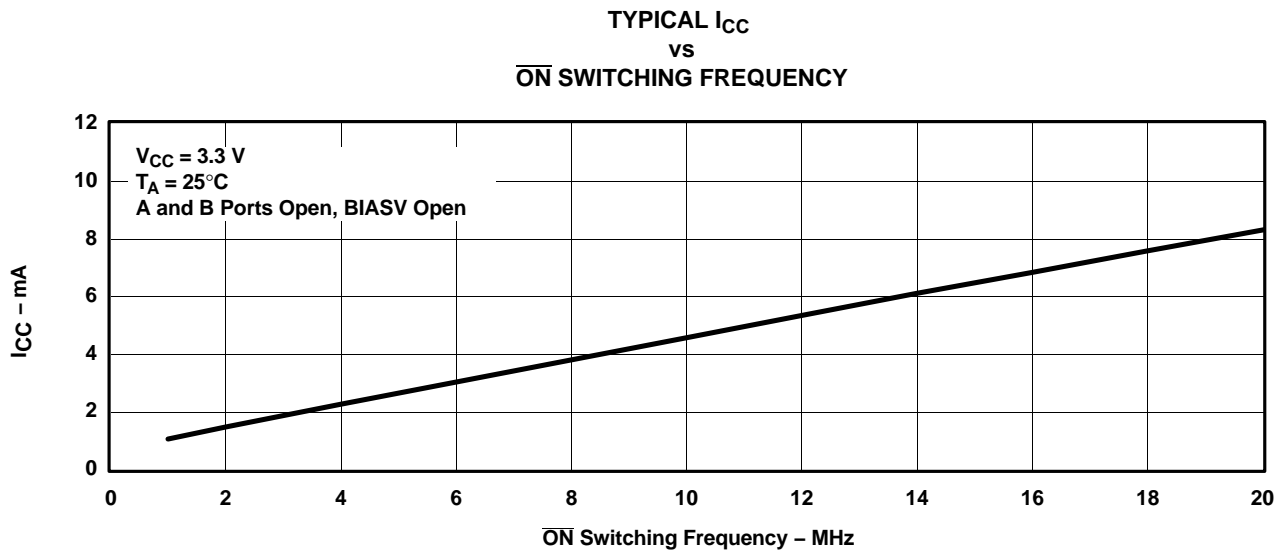
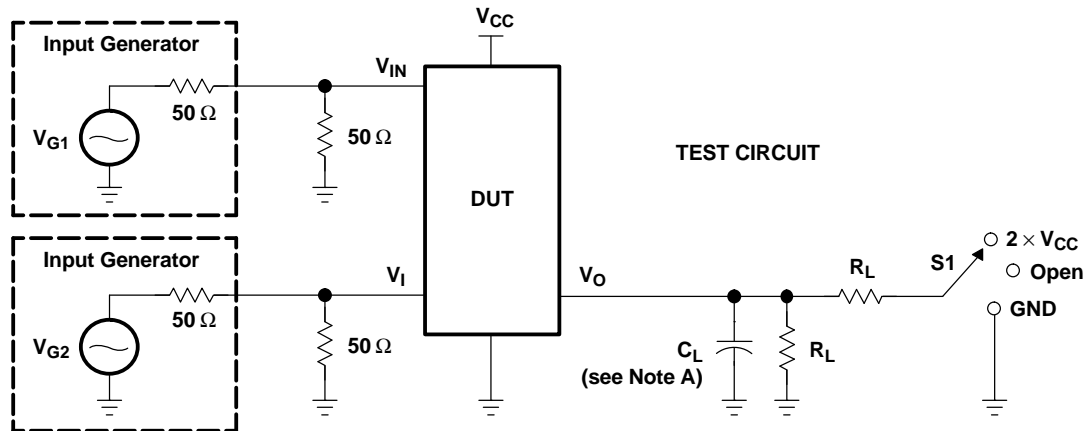


Figure 2. Typical  $I_{CC}$  vs  $\overline{ON}$  Switching Frequency

PARAMETER MEASUREMENT INFORMATION



TEST	V <sub>CC</sub>	S1	R <sub>L</sub>	V <sub>I</sub>	C <sub>L</sub>	V <sub>Δ</sub>
t <sub>pd(s)</sub>	2.5 V ± 0.2 V	Open	500 Ω	V <sub>CC</sub> or GND	30 pF	
	3.3 V ± 0.3 V	Open	500 Ω	V <sub>CC</sub> or GND	50 pF	
t <sub>PLZ</sub> /t <sub>PZL</sub>	2.5 V ± 0.2 V	2 × V <sub>CC</sub>	500 Ω	GND	30 pF	0.15 V
	3.3 V ± 0.3 V	2 × V <sub>CC</sub>	500 Ω	GND	50 pF	0.3 V
t <sub>PHZ</sub> /t <sub>PZH</sub>	2.5 V ± 0.2 V	GND	500 Ω	V <sub>CC</sub>	30 pF	0.15 V
	3.3 V ± 0.3 V	GND	500 Ω	V <sub>CC</sub>	50 pF	0.3 V



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES (t<sub>pd(s)</sub>)



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES:
- A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> ≤ 2.5 ns, t<sub>f</sub> ≤ 2.5 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd(s)</sub>. The t<sub>pd</sub> propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
  - H. All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74CB3Q6800DBQRE4	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
74CB3Q6800DBQRG4	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
74CB3Q6800DGVRE4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CB3Q6800DGVRG4	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CB3Q6800DBQR	ACTIVE	SSOP/QSOP	DBQ	24	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74CB3Q6800DGV	ACTIVE	TVSOP	DGV	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CB3Q6800PW	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CB3Q6800PWE4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CB3Q6800PWG4	ACTIVE	TSSOP	PW	24	60	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CB3Q6800PWR	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CB3Q6800PWRE4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CB3Q6800PWRG4	ACTIVE	TSSOP	PW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CB3Q6800DBQR	SSOP/ QSOP	DBQ	24	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74CB3Q6800DGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CB3Q6800PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CB3Q6800DBQR	SSOP/QSOP	DBQ	24	2500	346.0	346.0	33.0
SN74CB3Q6800DGVR	TVSOP	DGV	24	2000	346.0	346.0	29.0
SN74CB3Q6800PWR	TSSOP	PW	24	2000	346.0	346.0	33.0

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



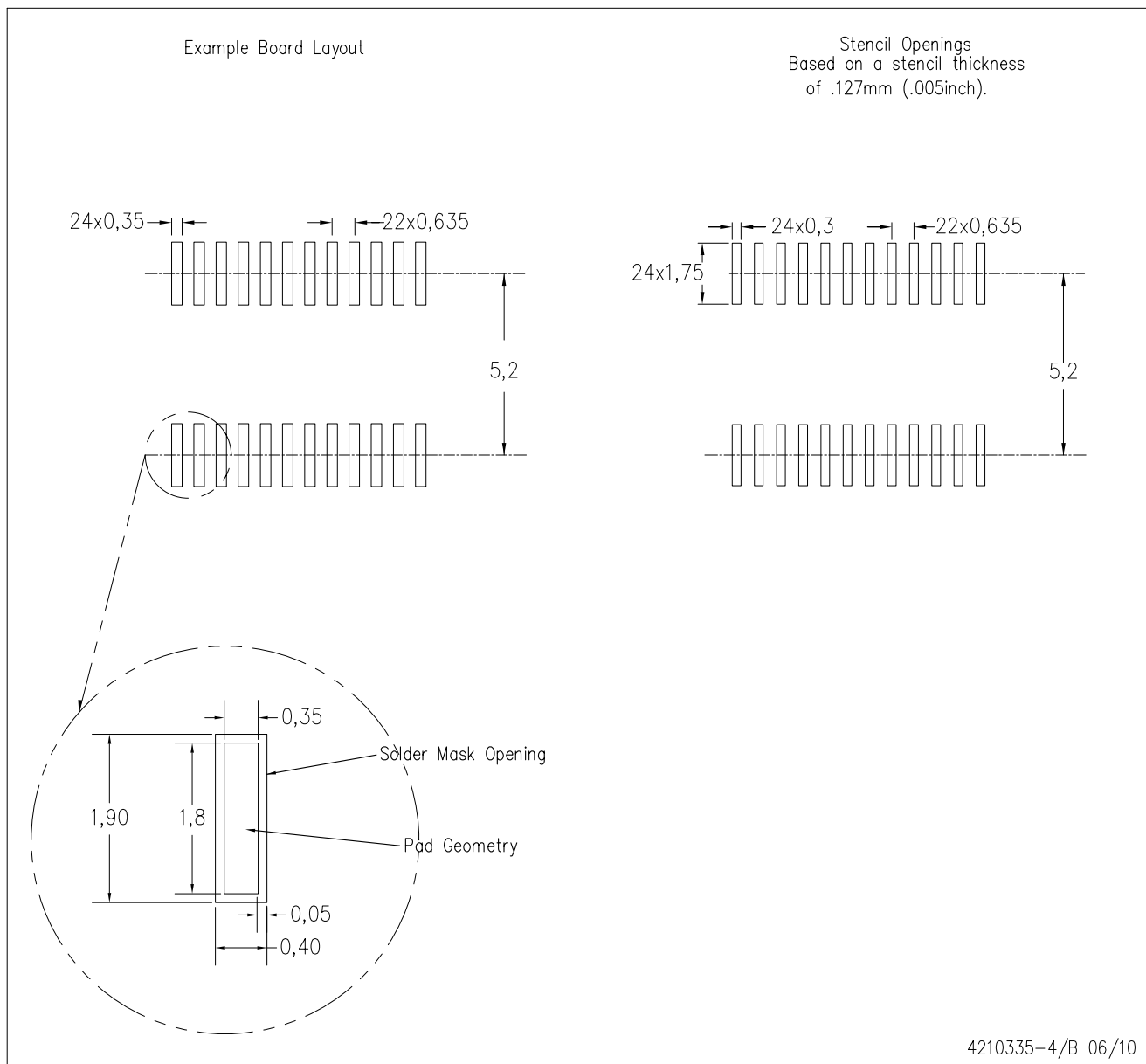
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- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



DBQ (R-PDSO-G24)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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